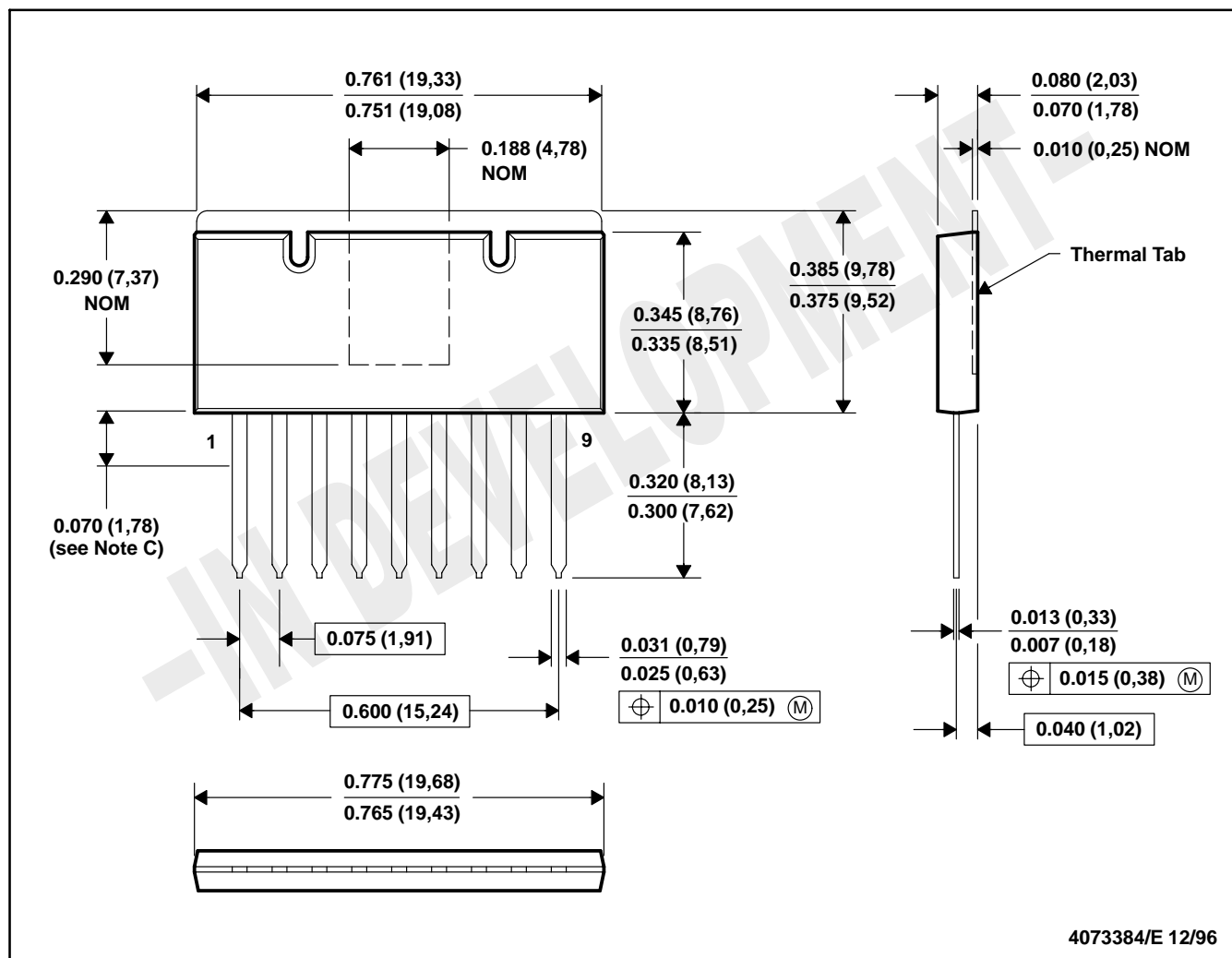


KTB (R-PSFM-T9)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Lead width not controlled in this area.  
 D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).

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